



Material Content Data Sheet



Sales Product Name		BTS7008-1EPP		Issued		3. October 2018			
MA#		MA002466278							
Package		PG-TSDSO-14-22		Weight*		64.91 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.856	1.32	1.32	13186	13186	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145		
	non noble metal	zinc	7440-66-6	0.038	0.06		581		
	non noble metal	iron	7439-89-6	0.754	1.16		11617		
wire	non noble metal	copper	7440-50-8	30.617	47.16	48.39	471708	484051	
	non noble metal	copper	7440-50-8	0.476	0.73	0.73	7328	7328	
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.14		1358	
encapsulation	plastics	epoxy resin	-	3.438	5.30		52966		
	inorganic material	silicondioxide	60676-86-0	25.857	39.84	45.28	398373	452697	
	leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25292	25292
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12573	12573	
glue	plastics	epoxy resin	-	0.055	0.09		853		
	noble metal	silver	7440-22-4	0.261	0.40	0.49	4020	4873	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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